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(54) **CONNECTOR ASSEMBLY AND MANUFACTURING METHOD THEREOF, AND ELECTRONIC DEVICE**

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(57) **ABSTRACT**

The technology of this application relates to a connector assembly including a metal housing, a conducting piece, a wire, and a shield layer. The metal housing includes a shield cavity. The conducting piece is accommodated in the shield cavity. The wire is partially located in the shield cavity and is electrically connected to one end of the conducting piece. The shield layer is wrapped around the wire. At least two electrical connecting parts are disposed on an outer surface of the shield layer. The at least two electrical connecting parts face different directions and are respectively electrically connected to parts, of the metal housing, that the at least two electrical connecting parts face, to reduce impact of crosstalk of the connector assembly. The connector assembly is intended to reduce impact of crosstalk of the connector assembly, to provide the connector assembly and the electronic device that meet an application requirement of 112 Gbps.